TC 7304A is a pure Ag via fill which provides excellent compatibility with Heraeus tape system of CT 700 and CT 800 during the co-firing process.

- Optimized for stencil printing of vias
- Compatible with other co-firing pastes and with various post firing pastes
- After firing, the paste can easily be soldered.
- Free of lead, nickel, cadmium and phthalate
- REACH\(^3\) and RoHS\(^4\) compliant

### Processing

1) Spatulate well prior to processing.

   When stored in a fridge: The paste should have acquired room temperature before being opened, to avoid condensation.

2) Print through a stencil.

3) Level at room temperature for 5 – 10 minutes.

4) Dry at max. 80 °C for 10 – 30 minutes.

5) Fire at 850 – 865 °C (peak) for up to 30 minutes, and with a total firing cycle time up to 10 hours (most often practicable in a box oven).

### Thinner

HVS 507
Legend:

1) Typical properties based on laboratory test methods. For optimum results all materials should be fired in a profiled furnace supplied with dried, hydrocarbon and other contaminant free air (PP-1)

2) Measured after printing with a metal stencil; thickness was c. 100 µm, and the resultant printed geometry was 40mm x 10mm.

3) REACH compliant according to the latest Annex XIV to Regulation (EC) of the European Parliament and of the council on the Registration, Evaluation, Authorisation and Restriction of Chemicals ("REACH") by European Chemicals Agency and its subsequent amendments; the material does not contain any substance listed in Annex XIV.

4) RoHS compliant according to the latest Directives (European Union) of Restriction of Hazardous Substances ("RoHS") and its subsequent amendments (including the exceptions related to Pb)

See the data sheet issue date (DD/MM/YY) as reference of validity of latest edition which is available on request.